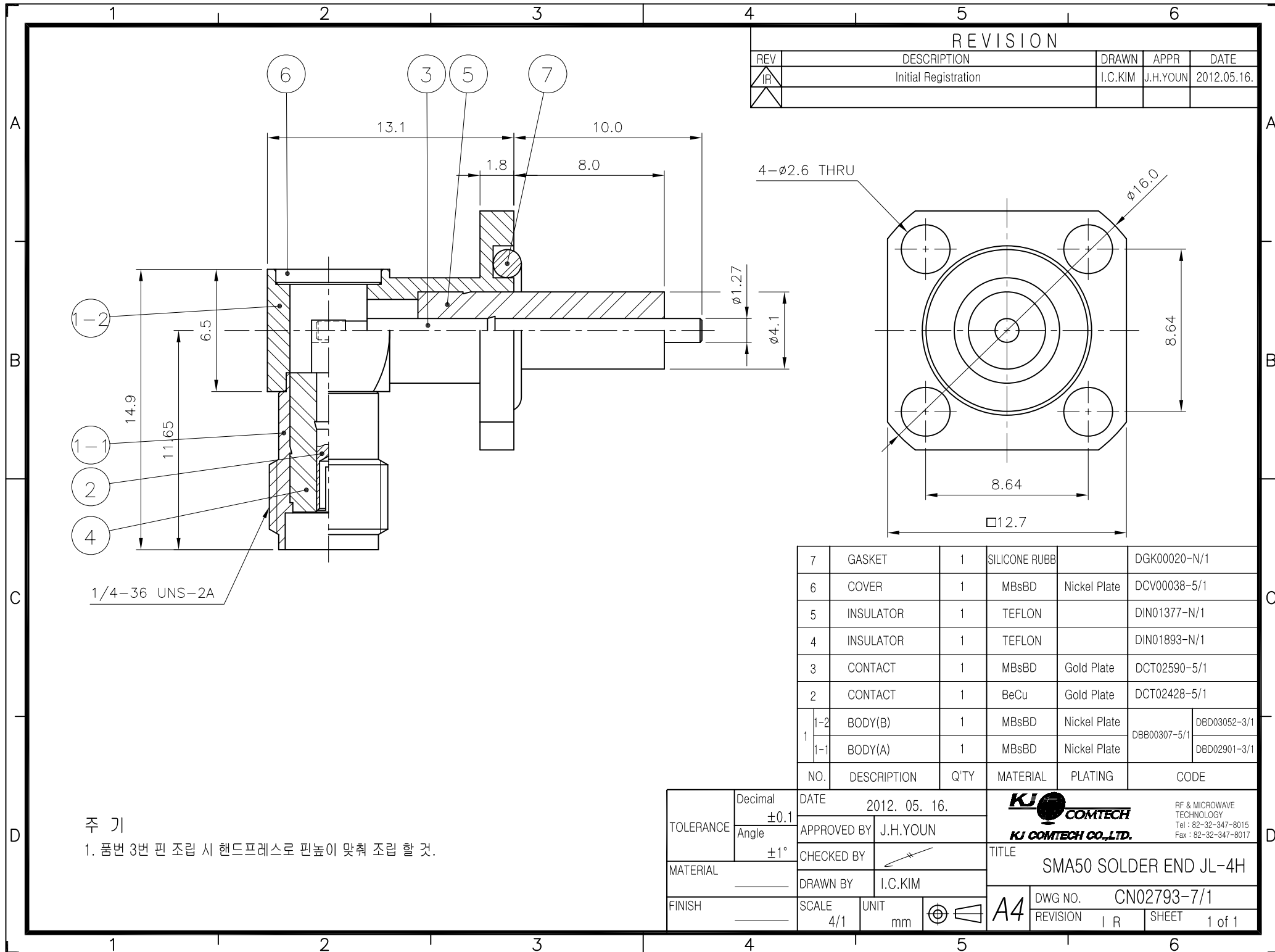




REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	J.H.YOUN	2012.05.16.

7	GASKET	1	SILICONE RUBB		DGK00020-N/1	
6	COVER	1	MBsBD	Nickel Plate	DCV00038-5/1	
5	INSULATOR	1	TEFLON		DIN01377-N/1	
4	INSULATOR	1	TEFLON		DIN01893-N/1	
3	CONTACT	1	MBsBD	Gold Plate	DCT02590-5/1	
2	CONTACT	1	BeCu	Gold Plate	DCT02428-5/1	
1	1-2 BODY(B)	1	MBsBD	Nickel Plate	DBB00307-5/1	DBD03052-3/1
	1-1 BODY(A)	1	MBsBD	Nickel Plate		DBD02901-3/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE	

주 기
1. 품번 3번 핀 조립 시 핸드프레스로 핀높이 맞춰 조립 할 것.

TOLERANCE	Decimal	DATE		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	±0.1	2012. 05. 16.			
	Angle	APPROVED BY		J.H.YOUN	
	±1°	CHECKED BY			
MATERIAL		DRAWN BY		TITLE	
		I.C.KIM		SMA50 SOLDER END JL-4H	
FINISH		SCALE	UNIT	A4	DWG NO.
		4/1	mm		
				REVISION	I R
				SHEET	1 of 1